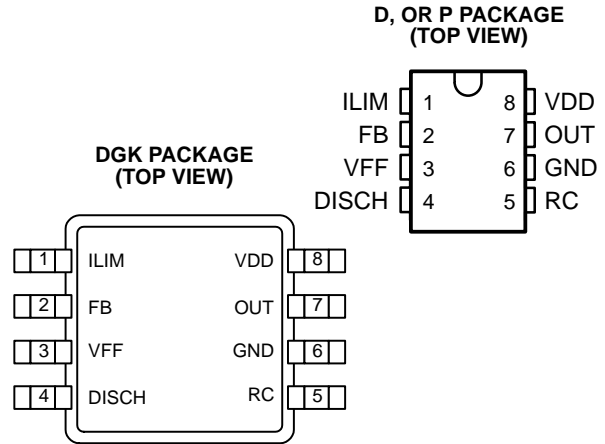


UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

- Greater Than 4-MHz Operation
- Integrated Oscillator / Voltage Feed Forward Compensation
- >4:1 Input Voltage Range
- 25-ns Current Limit Delay
- Programmable Maximum Duty Cycle Clamp
- Optocoupler Interface
- 50- μ A Start-Up Current
- 4.2-mA Operating Current @ 1 MHz
- Smallest Footprint of the 8-pin MSOP Package Minimizes Board Area and Height



description

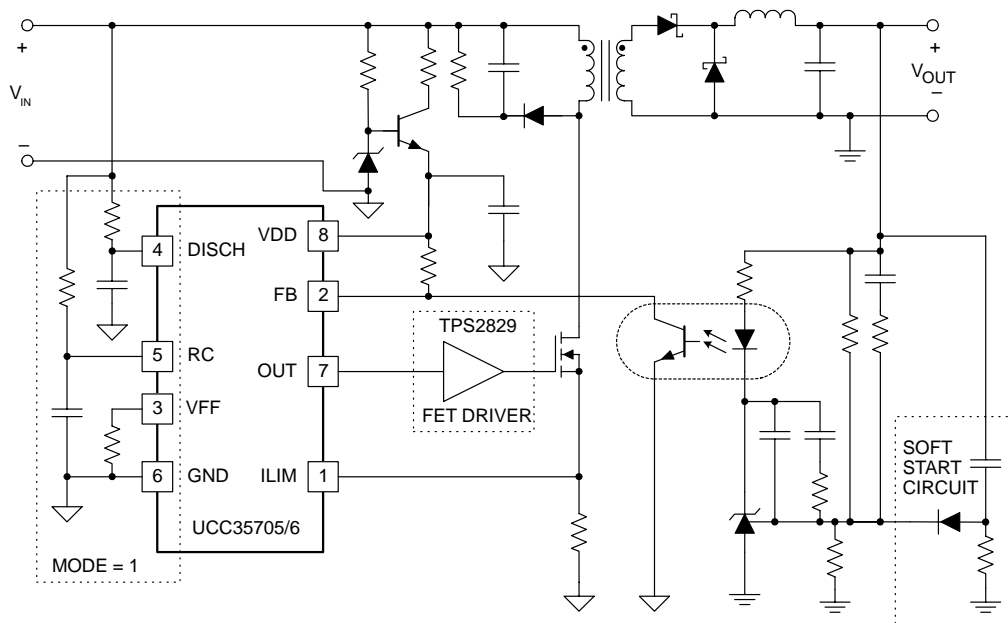
The UCC35705 and UCC35706 devices are 8-pin voltage mode primary side controllers with fast over-current protection. These devices are used as core high-speed building blocks in high performance isolated and non-isolated power converters.

UCC35705/UCC35706 devices feature a high speed oscillator with integrated feed-forward compensation for improved converter performance. A typical current sense to output delay time of 25 ns provides fast response to overload conditions. The IC also provides an accurate programmable maximum duty cycle clamp for increased protection which can also be disabled for the oscillator to run at maximum possible duty cycle.

Two UVLO options are offered. The UCC35705 with lower turn-on voltage is intended for dc-to-dc converters while the higher turn-on voltage and the wider UVLO range of the UCC35706 is better suited for offline applications.

The UCC35705/UCC35706 family is offered in 8-pin MSOP (DGK), SOIC (D) and PDIP (P) packages.

typical application schematic



UDG-99181



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**
www.ti.com

Copyright © 2001, Texas Instruments Incorporated

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage	15 V
Input voltage (VFF,RC,ILIM)	7 V
Input voltage (FB)	15 V
Input current (DISCH)	1 mA
Output current (OUT) dc	±20 mA
Storage temperature, T _{stg}	–65°C to 150°C
Junction temperature, T _J	–55°C to 150°C
Lead temperature (soldering, 10 sec.)	300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ All voltages are with respect to GND. Currents are positive into, negative out of the specified terminal. Consult Packaging Section of the *Power Supply Control Data Book (TI Literature Number SLUD003)* for thermal limitations and considerations of packages.

AVAILABLE OPTIONS

T _A = T _J	Packaged Devices			
	UVLO Option	SOIC-8 Small Outline (D)†	PDIP-8 Plastic Dip (P)	MSOP-8 Small Outline (DGK)†
–40°C to 85°C	8.8V/8V	UCC25705D	UCC25705P	UCC25705DGK
	12V/8V	UCC25706D	UCC25706P	UCC25706DGK
0°C to 70°C	8.8V/8V	UCC35705D	UCC35705P	UCC35705DGK
	12V/8V	UCC35706D	UCC35706P	UCC35706DGK

† D (SOIC–8) and DGK (MSOP–8) packages are available taped and reeled. Add R suffix to device type (e.g. UCC35705DR) to order quantities of 2500 devices per reel for SOIC-8 and 2000 devices per reel for the MSOP-8.

electrical characteristics, V_{DD} = 11 V, V_{IN} = 30 V, R_T = 47 k, R_{DISCH} = 400 k, R_{FF} = 14 k, C_T = 220 pF, C_{VDD} = 0.1 μF, and no load on the outputs, 0°C ≤ T_A ≤ 70°C for the UCC3570x and –40°C ≤ T_A ≤ 85°C for the UCC2570x, T_A = T_J, (unless otherwise specified)

UVLO section (UCCx5705)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Start threshold		8.0	8.8	9.6	V
Stop threshold		7.4	8.2	9.0	V
Hysteresis		0.3	0.6	1.0	V

UVLO section (UCCx5706)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Start threshold		11.2	12.0	12.8	V
Stop threshold		7.2	8.0	8.8	V
Hysteresis		3.5	4.0	4.5	V

supply current section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Start-up current	V _{DD} = UVLO start – 1 V, V _{DD} comparator off		30	90	μA
I _{DD} active	V _{DD} comparator on, oscillator running at 1 MHz		4.2	5.0	mA

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

electrical characteristics, $V_{DD} = 11\text{ V}$, $V_{IN} = 30\text{ V}$, $R_T = 47\text{ k}$, $R_{DISCH} = 400\text{ k}$, $R_{FF} = 14\text{ k}$, $C_T = 220\text{ pF}$, $C_{VDD} = 0.1\text{ }\mu\text{F}$, and no load on the outputs, $0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$ for the UCC3570x and $-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$ for the UCC2570x, $T_A = T_J$, (unless otherwise specified)

line sense section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Low line comparator threshold		0.95	1.00	1.05	V
Input bias current (VFF)		-100		100	nA

oscillator section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Frequency	VFF = 1.2 V to 4.8 V	0.9	1.0	1.1	MHz
CT peak voltage	VFF = 1.2 V, See Note 1		1.2		V
	VFF = 4.8 V, See Note 1		4.8		V
CT valley voltage	See Note 1		0		V

NOTE 1: Ensured by design. Not production tested.

current limit section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Input bias current		0.2	-0.2	-1	μA
Current limit threshold		180	200	220	mV
Propagation delay, ILIM to OUT	50 mV overdrive		25	35	ns

pulse width modulator section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
FB input impedance	$V_{FB} = 3\text{ V}$	30	50	90	$\text{k}\Omega$
Minimum duty cycle	$V_{FB} < 2\text{ V}$			0	%
Maximum duty cycle	$V_{FB} = V_{DD}$, $F_{OSC} = 1\text{ MHz}$	70	75	80	%
	$V_{DISCH} = 0\text{ V}$, $F_{OSC} = 1\text{ MHz}$		93		%
PWM gain	VFF = 2.5 V, MODE = 1		12		%/V
Propagation delay, PWM to OUT			65	120	ns

output section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
VOH	$I_{OUT} = -5\text{ mA}$, V_{DD} – output		0.3	0.6	V
VOL	$I_{OUT} = 5\text{ mA}$		0.15	0.4	V
Rise time	$C_{LOAD} = 50\text{ pF}$		10	25	ns
Fall time	$C_{LOAD} = 50\text{ pF}$		10	25	ns

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

pin descriptions

DISCH: A resistor to VIN sets the oscillator discharge current programming a maximum duty cycle. When grounded, an internal comparator switches the oscillator to a quick discharge mode. A small 100-pF capacitor between DISCH and GND may reduce oscillator jitter without impacting feed-forward performance. I_{DISCH} must be between 25 μ A and 250 μ A over the entire V_{IN} range.

FB: Input to the PWM comparator. This pin is intended to interface with an optocoupler. Input impedance is 50-k Ω typical.

GND: Ground return pin.

ILIM: Provides a pulse-by-pulse current limit by terminating the PWM pulse when the input is above 200 mV. This provides a high speed (25 ns typical) path to reset the PWM latch, allowing for a pulse-by-pulse current limit.

OUT: The output is intended to drive an external FET driver or other high impedance circuits, but is not intended to directly drive a power MOSFET. This improves the controller's noise immunity. The output resistance of the PWM controller, typically 60 Ω pull-up and 30 Ω pull-down, will result in excessive rise and fall times if a power MOSFET is directly driven at the speeds for which the UCC35705/6 is optimized.

RC: The oscillator can be configured to provide a maximum duty cycle clamp. In this mode the on-time is set by RT and CT, while the off-time is set by RDISCH and CT. Since the voltage ramp on CT is proportional to VIN, feed-forward action is obtained. Since the peak oscillator voltage is also proportional to VIN, constant frequency operation is maintained over the full power supply input range. When the DISCH pin is grounded, the duty cycle clamp is disabled. The RC pin then provides a low impedance path to ground CT during the off time.

VDD: Power supply pin. This pin should be bypassed with a 0.1- μ F capacitor for proper operation. The undervoltage lockout function of the UCC35705/6 allows for a low current startup mode and ensures that all circuits become active in a known state. The UVLO thresholds on the UCC35705 are appropriate for a dc-to-dc converter application. The wider UVLO hysteresis of the UCC35706 (typically 4 V) is optimized for a bootstrap startup mode from a high impedance source.

VFF: The feed-forward pin provides the controller with a voltage proportional to the power supply input voltage. When the oscillator is providing a duty cycle clamp, a current of $2 \times I_{DISCH}$ is sourced from the VFF pin. A single resistor RFF between VFF and GND then set VFF to:

$$VFF \approx VIN \times \left(\frac{2 \times R_{FF}}{2 \times R_{FF} + R_{DISCH}} \right)$$

When the DISCH pin is grounded and the duty cycle clamp is not used, the internal current source is disabled and a resistor divider from VIN is used to set VFF. In either case, when the voltage on VFF is less than 1.0 V, both the output and oscillator are disabled.

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

pin descriptions (continued)

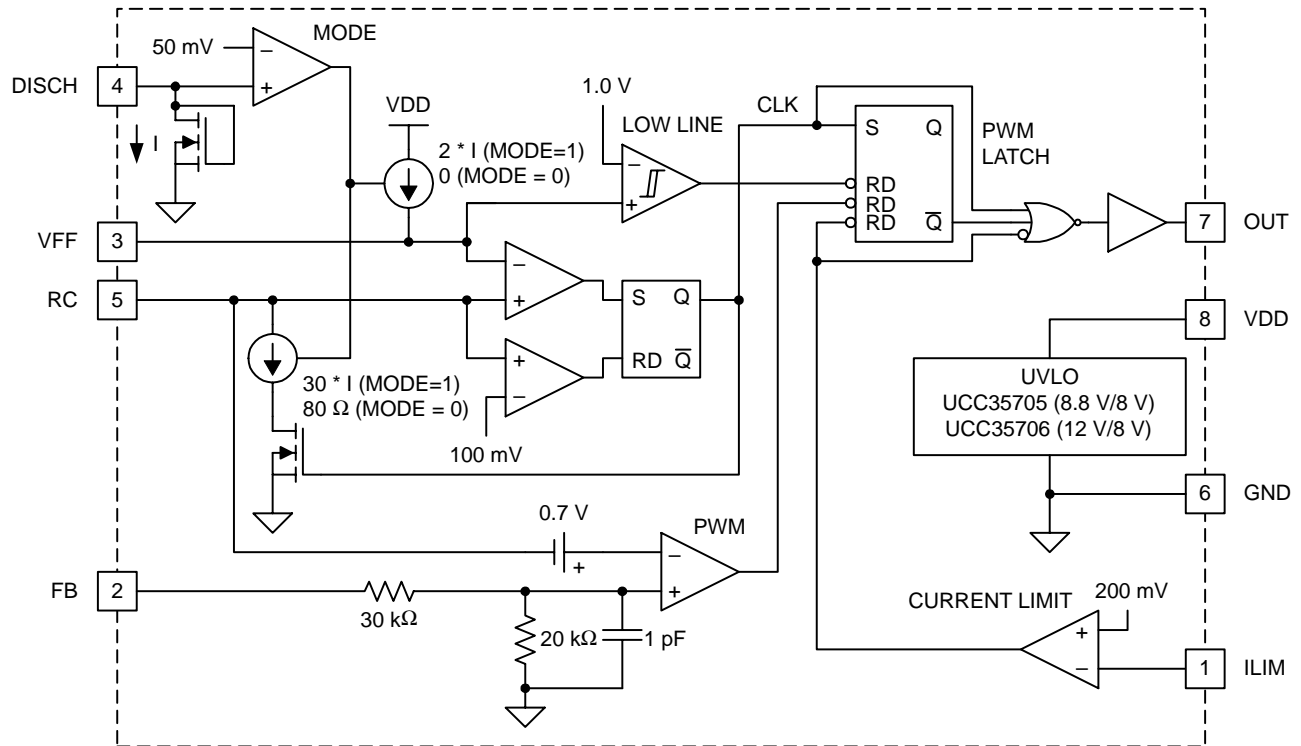


Figure 1. Block Diagram

FUNCTIONAL DESCRIPTION

oscillator and PWM

The oscillator can be programmed to provide a duty cycle clamp or be configured to run at the maximum possible duty cycle.

The PWM latch is set during the oscillator discharge and is reset by the PWM comparator when the C_T waveform is greater than the feedback voltage. The voltage at the FB pin is attenuated before it is applied to the PWM comparator. The oscillator ramp is shifted by approximately 0.65-V at room temperature at the PWM comparator. The offset has a temperature coefficient of approximately $-2 \text{ mV}/^\circ\text{C}$.

The ILIM comparator adds a pulse by pulse current limit by resetting the PWM latch when $V_{ILIM} > 200 \text{ mV}$. The PWM latch is also reset by a low line condition ($V_{FF} < 1.0 \text{ V}$).

All reset conditions are dominant; asserting any output will force a zero duty cycle output.

oscillator with duty cycle clamp (MODE = 1)

The timing capacitor C_T is charged from ground to VFF through R_T . The discharge path is through an on-chip current sink that has a value of $30 \times I_{DISCH}$, where I_{DISCH} is the current through the external resistor R_{DISCH} . Since the charge and discharge currents are both proportional to V_{IN} , their ratio, and the maximum duty cycle remains constant as V_{IN} varies.

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

FUNCTIONAL DESCRIPTION

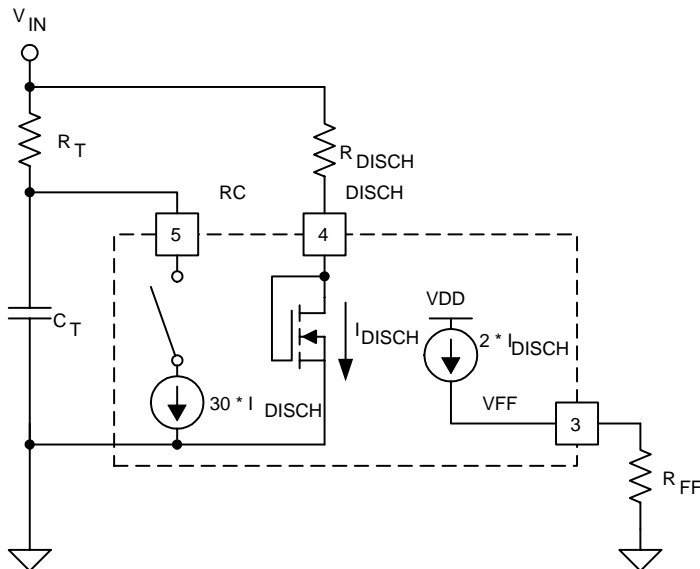


Figure 2. Duty Cycle Clamp (MODE = 1)

The on-time is approximately:

$$T_{ON} = \alpha \times R_T \times C_T \quad \text{where } \alpha = \frac{V_{FF}}{V_{IN}} \approx \frac{2 \times R_{FF}}{R_{DISCH}}$$

The off-time is:

$$T_{OFF} = \alpha \times \frac{C_T \times (R_T \times R_{DISCH})}{30 \times (R_T - R_{DISCH})}$$

The frequency is:

$$f = \left(\frac{1}{\alpha \times R_T \times C_T} \right) \times \frac{1}{1 + \frac{R_{DISCH}}{30 \times (R_T - R_{DISCH})}}$$

The maximum duty cycle is:

$$\text{Duty Cycle} = \frac{T_{ON}}{T_{ON} + T_{OFF}} = \left(1 - \frac{R_{DISCH}}{30 \times R_T} \right)$$

FUNCTIONAL DESCRIPTION

component selection for oscillator with duty cycle clamp (MODE = 1)

For a power converter with the following specifications:

- $V_{IN(min)} = 18\text{ V}$
- $V_{IN(max)} = 75\text{ V}$
- $V_{IN(shutdown)} = 15\text{ V}$
- $F_{OSC} = 1\text{ MHz}$
- $D_{MAX} = 0.78$ at $V_{IN(min)}$

In this mode, the on-time is approximately:

- $T_{ON(max)} = 780\text{ ns}$
- $T_{OFF(min)} = 220\text{ ns}$
- $V_{FF(min)} = \frac{18}{15} = 1.20\text{ V}$

(1) Pick $C_T = 220\text{ pF}$.

(2) Calculate R_T .

$$R_T = \frac{V_{IN(min)} \times T_{ON(max)}}{V_{FF(min)} \times C_T}$$

$R_T = 51.1\text{ k}\Omega$

(3) R_{DISCH}

$$R_{DISCH} = \frac{30 \times R_T}{1 + \left[\frac{\left(\frac{V_{FF(min)}}{V_{IN(min)}} \right) \times R_T \times C_T}{T_{OFF(min)}} \right]}$$

$R_{DISCH} = 383\text{ k}\Omega$.

I_{DISCH} must be between $25\text{ }\mu\text{A}$ and $250\text{ }\mu\text{A}$ over the entire V_{IN} range.

With the calculated values, I_{DISCH} ranges from $44\text{ }\mu\text{A}$ to $193\text{ }\mu\text{A}$, within the allowable range. If I_{DISCH} is too high, C_T must be decreased.

(4) R_{FF}

$$R_{FF} = \frac{V_{FF(min)} \times R_{DISCH}}{2 \times (V_{IN(min)} - 1)}$$

The nearest 1% standard value to the calculated value is 13.7 k .

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

FUNCTIONAL DESCRIPTION

oscillator without duty cycle clamp (MODE = 0)

In this mode, the timing capacitor is discharged through a low impedance directly to ground. The DISCH pin is externally grounded. A comparator connected to DISCH senses the ground connection and disables both the discharge current source and VFF current source. A resistor divider is now required to set VFF.

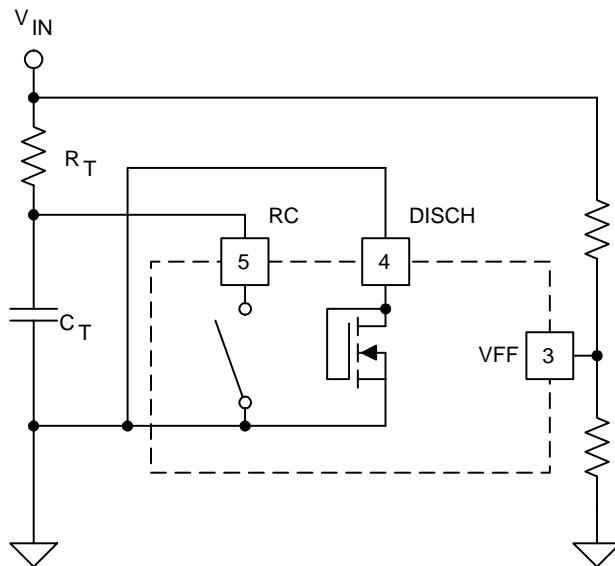


Figure 3. Oscillator Without Clamp (MODE = 0)

In this mode, the on-time is approximately:

$$T_{ON} = \alpha \times R_T \times C_T \quad \text{where } \alpha = \frac{V_{FF}}{V_{IN}}$$

The off-time is:

$$T_{OFF} \approx 75 \text{ ns}$$

The frequency is:

$$f = \frac{1}{\alpha \times R_T \times C_T + 75 \text{ ns}}$$

FUNCTIONAL DESCRIPTION

component selection for oscillator without duty cycle clamp (MODE = 0)

For a power converter with the following specifications:

- $V_{IN(min)} = 18\text{ V}$
- $V_{IN(max)} = 75\text{ V}$
- $V_{IN(shutdown)} = 15\text{ V}$
- $F_{OSC} = 1\text{ MHz}$

With these specifications,

$$V_{FF(min)} = \frac{18}{15} = 1.2\text{ V}$$

(1) Pick $C_T = 220\text{ pF}$

(2) Calculate R_T .

$$R_T = \frac{V_{IN(min)} \times \left(\frac{1}{F_{OSC}} - 75\text{ ns} \right)}{C_T}$$

TYPICAL CHARACTERISTICS

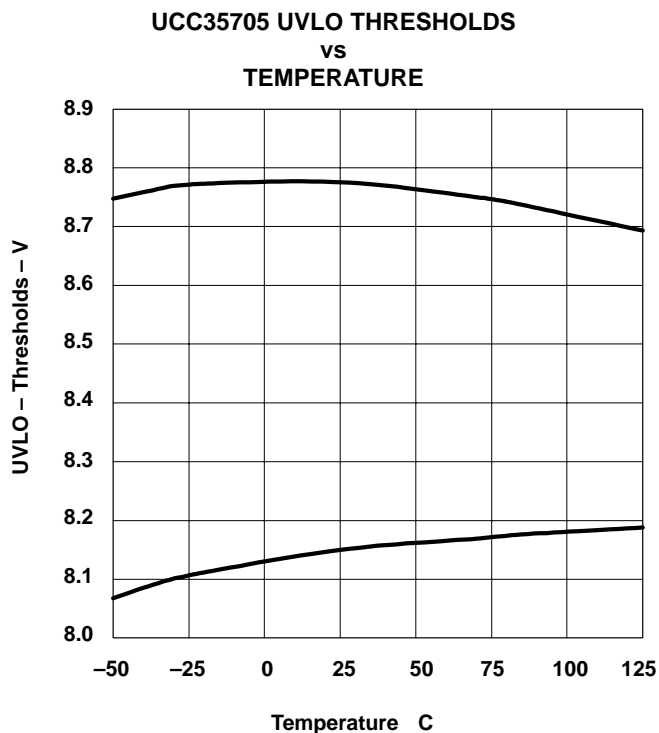


Figure 4

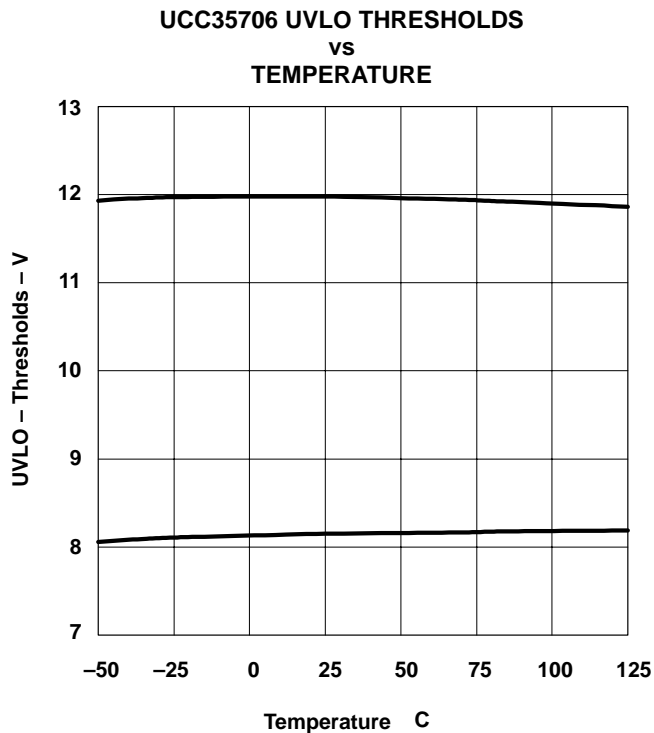


Figure 5

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

TYPICAL CHARACTERISTICS

OPERATING CURRENT (AT 1mHz)
vs
TEMPERATURE

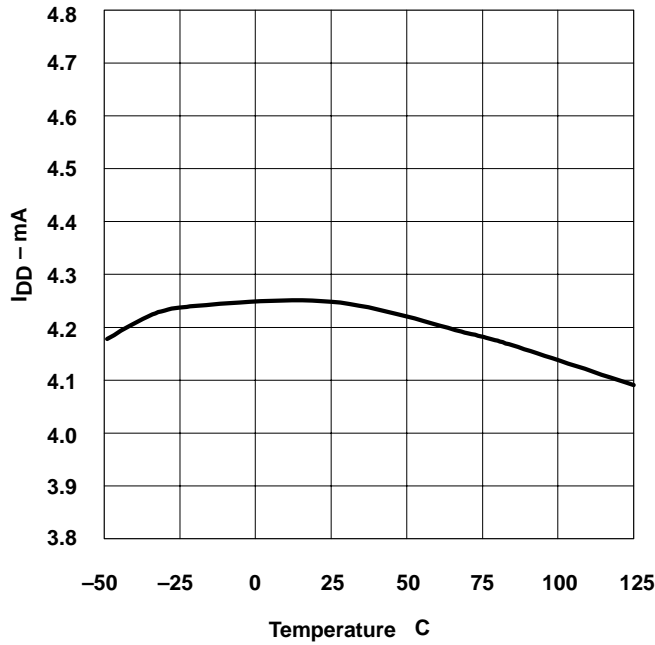


Figure 6

LOW-LINE THRESHOLD
vs.
TEMPERATURE

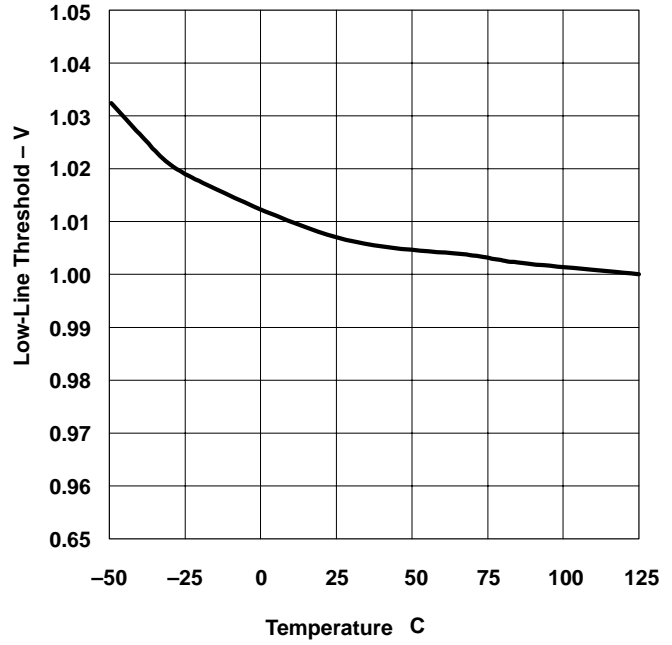


Figure 7

OSCILLATOR FREQUENCY
vs
TEMPERATURE

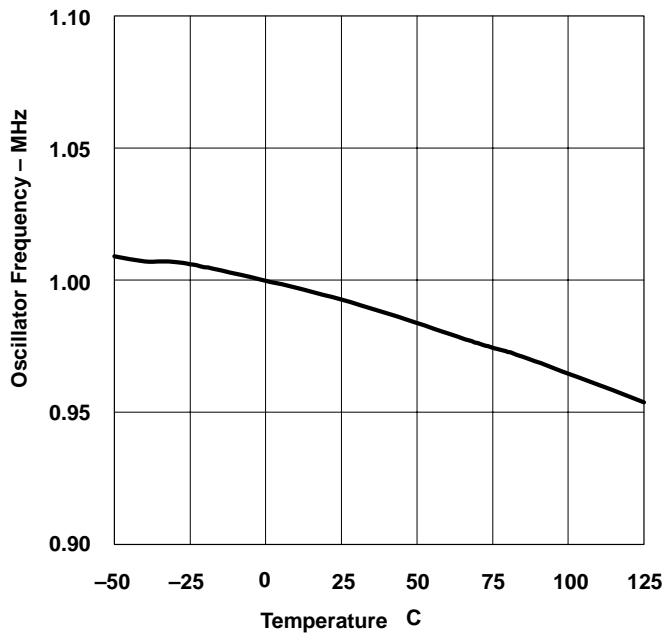


Figure 8

PROGRAMMABLE MAXIMUM
DUTY CYCLE
vs
TEMPERATURE

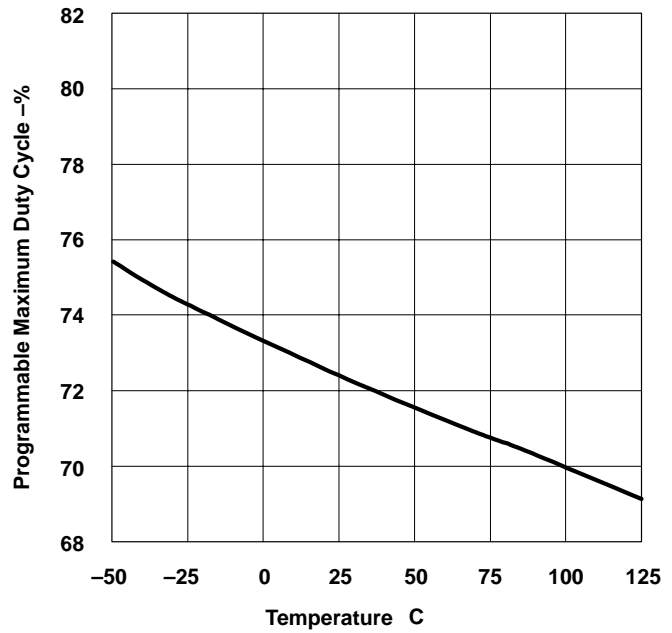


Figure 9

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

TYPICAL CHARACTERISTICS

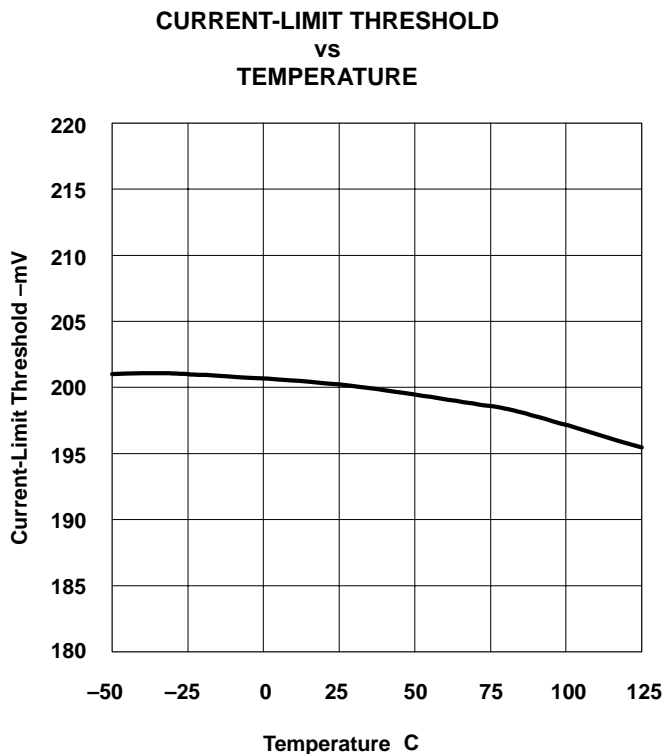


Figure 10

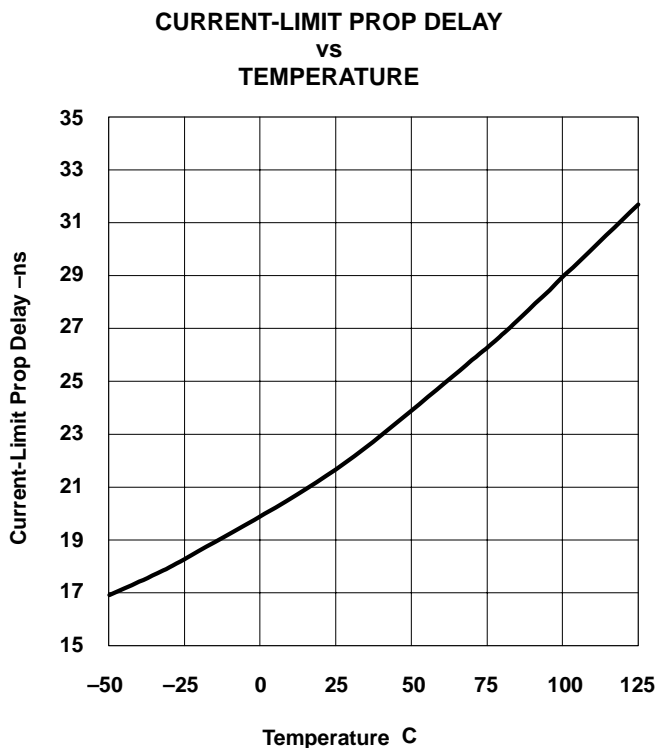


Figure 11

UCC25705, UCC25706, UCC35705, UCC35706 HIGH-SPEED VOLTAGE MODE PULSE WIDTH MODULATOR

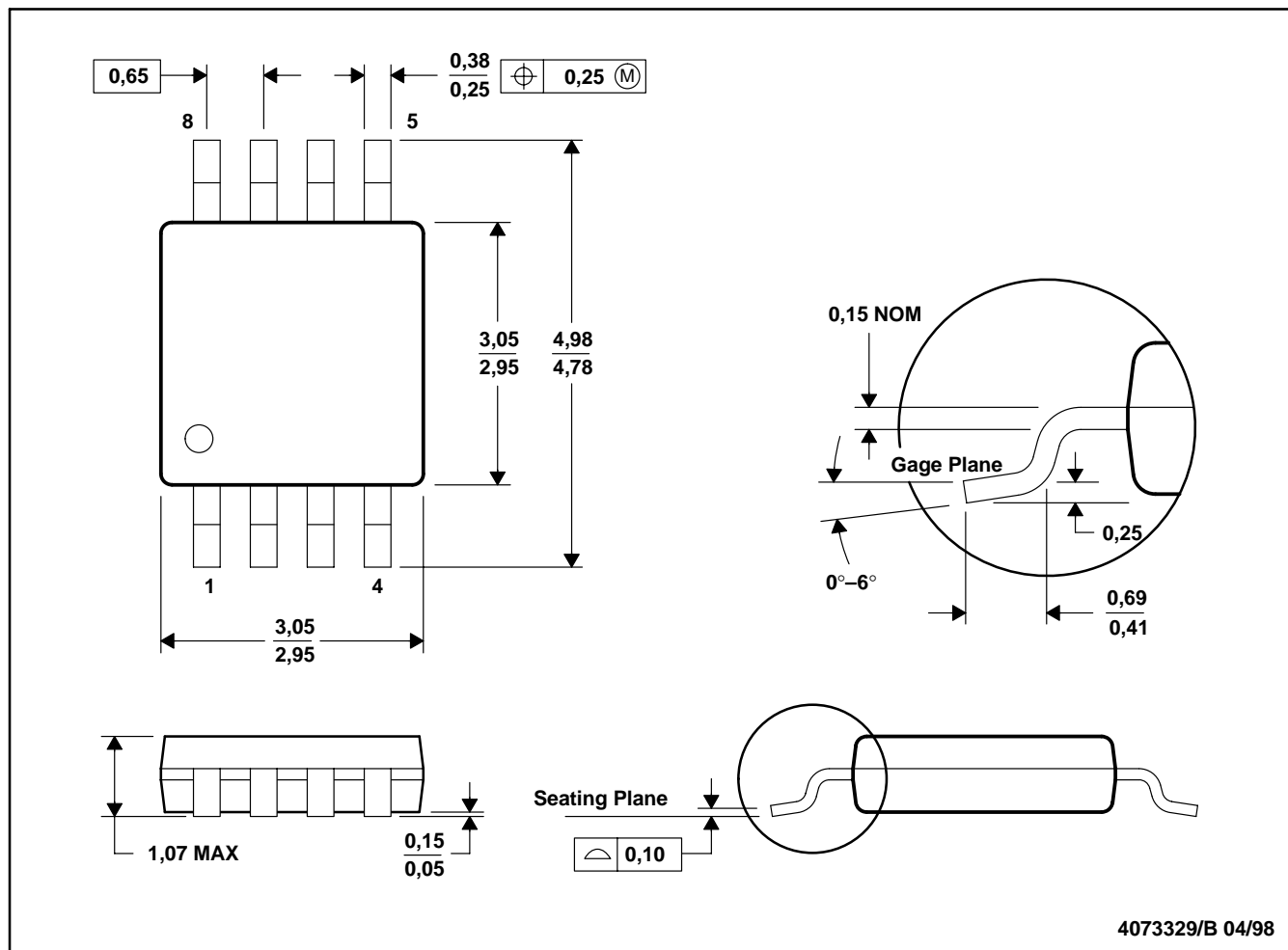
SLUS473A – NOVEMBER 1999 – REVISED MARCH 2001

MECHANICAL DATA

Detailed package drawing for MSOP-8 (DGK) is shown below. For SOIC-8 (D) and PDIP-8 (P) package drawings, consult Packaging Section of the *Power Supply Control Data Book (TI Literature Number SLUD003)*.

DGK (MSOP-8)

MINI SMALL OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. Falls within JEDEC MO-187

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UCC25705D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DGK	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DGKG4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DGKTR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DGKTRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25705P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC25705PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC25706D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25706DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25706DGK	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25706DGKG4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC25706P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC25706PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC35705D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DGK	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DGKG4	ACTIVE	MSOP	DGK	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DGKTR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DGKTRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35705P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UCC35705PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC35706D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35706DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35706DGK	ACTIVE	MSOP	DGK	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35706DGKG4	ACTIVE	MSOP	DGK	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC35706P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UCC35706PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC25705DGKTR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
UCC25705DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UCC35705DGKTR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
UCC35705DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC25705DGKTR	MSOP	DGK	8	2500	346.0	346.0	29.0
UCC25705DTR	SOIC	D	8	2500	346.0	346.0	29.0
UCC35705DGKTR	MSOP	DGK	8	2500	346.0	346.0	29.0
UCC35705DTR	SOIC	D	8	2500	346.0	346.0	29.0

DGK (S-PDSO-G8)

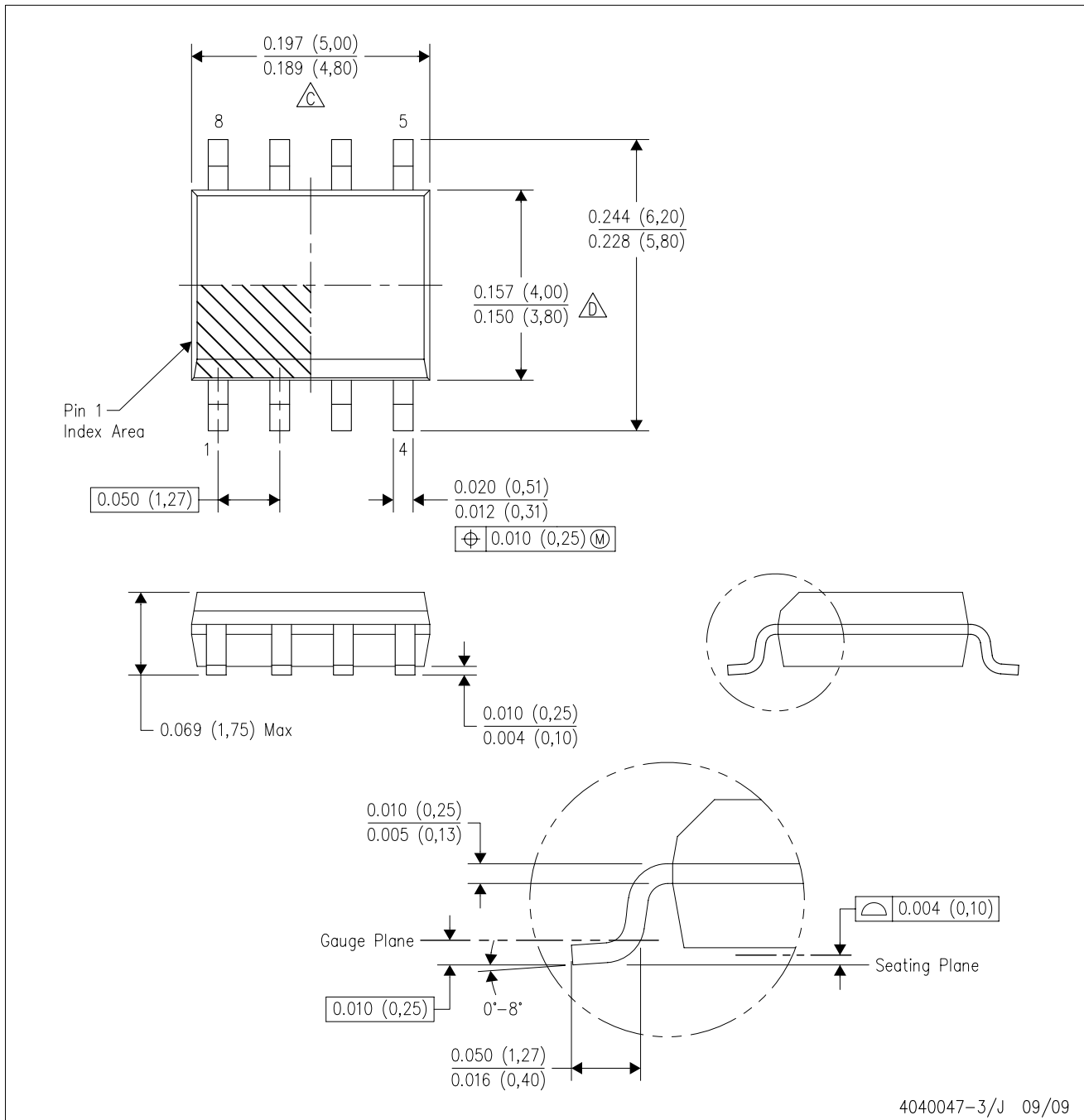
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2009, Texas Instruments Incorporated